



Material Content Data Sheet



Sales Product Name		BTS730		Issued		25. January 2018			
MA#		MA001172438							
Package		PG-DSO-20-83		Weight*		488.39 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	9.615	1.97	1.97	19688	19688	
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		79		
	non noble metal	zinc	7440-66-6	0.155	0.03		318		
	non noble metal	iron	7439-89-6	3.104	0.64		6356		
wire	non noble metal	copper	7440-50-8	126.041	25.81	26.49	258075	264828	
	noble metal	gold	7440-57-5	1.373	0.28	0.28	2811	2811	
	encapsulation	organic material	carbon black	1333-86-4	0.682	0.14		1396	
encapsulation	plastics	epoxy resin	-	31.373	6.42		64237		
	inorganic material	silicondioxide	60676-86-0	308.954	63.26	69.82	632596	698229	
leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5622	5622	
plating	noble metal	silver	7440-22-4	1.486	0.30	0.30	3043	3043	
glue	plastics	epoxy resin	-	0.494	0.10		1011		
	noble metal	silver	7440-22-4	2.329	0.48	0.58	4768	5779	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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